



IPC/JEDEC-9707
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Spherical Bend Test Method
for Characterization of Board
Level Interconnects

A standard developed by IPC

Association Connecting Electronics Industries



The Principles of Standardization

In May 1995 the IPC's Technical Activities Executive Committee (TAEC) adopted Principles of Standardization as a guiding principle of IPC's standardization efforts.

Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Spherical Bend Test Method for Characterization of Board Level Interconnects

Developed by the SMT Attachment Reliability Test Methods Task
Group (6-10d) of the Product Reliability Committee (6-10) of IPC

Users of this publication are encouraged to participate in the
development of future revisions.

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